

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	I_D
100V	130mΩ@10V	3A
	140mΩ@4.5V	

Feature

- High density cell design for ultra low Rdson
- Fully characterized Avalanche voltage and current

Application

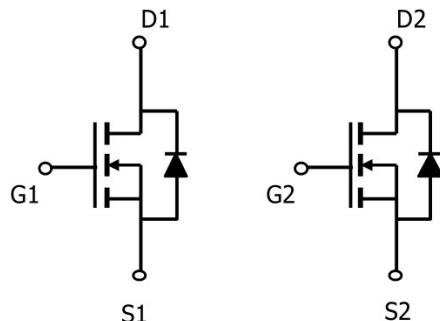
- Power switching application
- Hard Switched and High Frequency Circuits
- Uninterruptible Power Supply

Package

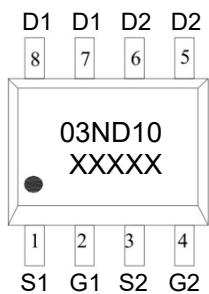


SOP-8

Circuit diagram



Marking



Absolute maximum ratings (Ta=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DS}	100	V
Gate-Source Voltage	V _{GS}	±20	V
Continuous Drain Current	I _D	3	A
Pulsed Drain Current	I _{DM}	12	A
Power Dissipation	P _D	2	W
Thermal Resistance from Junction to Ambient	R _{θJA}	85	°C/W
Junction Temperature	T _J	150	°C
Storage Temperature	T _{STG}	-55 ~ +150	°C

Electrical characteristics (T_A=25 °C, unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	100			V
Zero gate voltage drain current	I _{DSS}	V _{DS} = 20V, V _{GS} = 0V			1	μA
Gate-body leakage current	I _{GSS}	V _{GS} = ±12V, V _{DS} = 0V			±100	nA
Gate threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	1	1.5	2	V
Drain-source on-resistance	R _{DS(on)}	V _{GS} = 10V, I _D = 3A		95	130	mΩ
		V _{GS} = 4.5V, I _D = 1A		100	140	
Dynamic characteristics¹⁾						
Input Capacitance	C _{iss}	V _{DS} = 50V, V _{GS} = 0V, f = 1MHz		730		pF
Output Capacitance	C _{oss}			37		
Reverse Transfer Capacitance	C _{rss}			27		
Total Gate Charge	Q _g	V _{DS} = 50V, V _{GS} = 10V, I _D = 3A		21.5		nC
Gate-Source Charge	Q _{gs}			3.2		
Gate-Drain Charge	Q _{gd}			6		
Turn-on delay time	t _{d(on)}	V _{DD} = 50V, R _L = 15Ω V _{GS} = 10V, R _G = 2.5Ω		11		nS
Turn-on rise time	t _r			7.4		
Turn-off delay time	t _{d(off)}			35		
Turn-off fall time	t _f			9.1		
Source-Drain Diode characteristics						
Diode Forward voltage	V _{DS}	V _{GS} = 0V, I _S = 3A			1.2	V

Notes:

1) Guaranteed by design, not subject to production testing.



Typical Characteristics

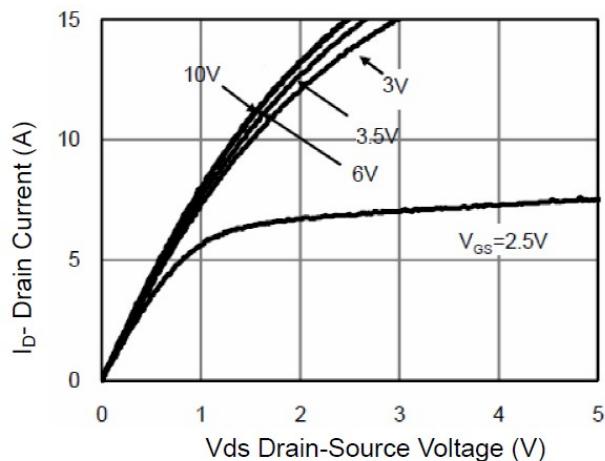


Figure 1 Output Characteristics

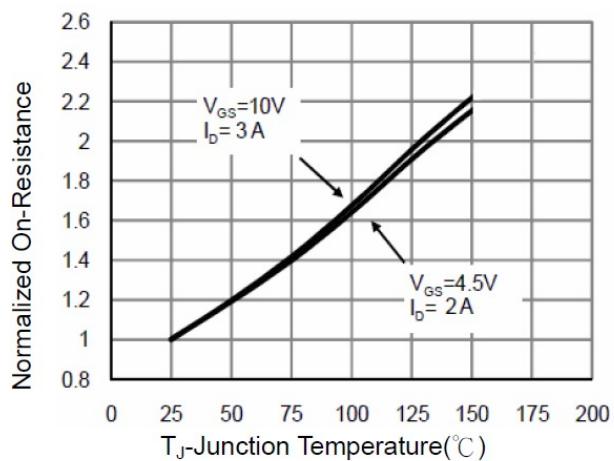


Figure 2 $R_{DS(on)}$ -Junction Temperature

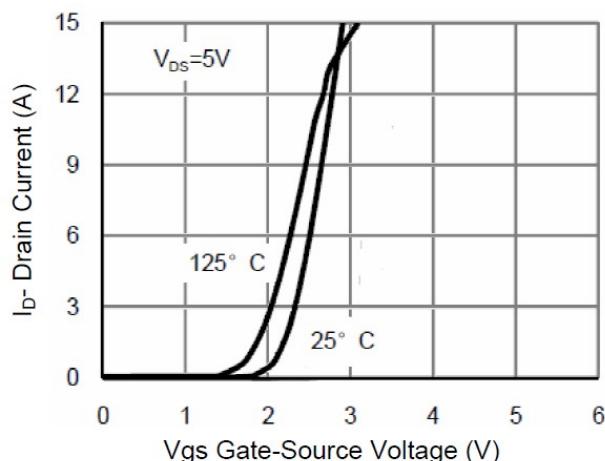


Figure 3 Transfer Characteristics

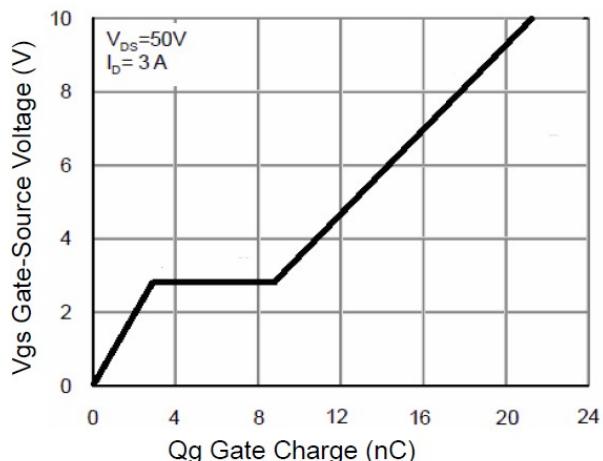


Figure 4 Gate Charge

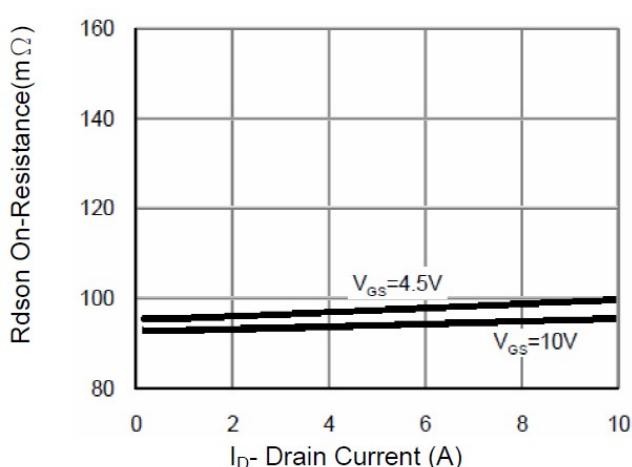


Figure 5 $R_{DS(on)}$ - Drain Current

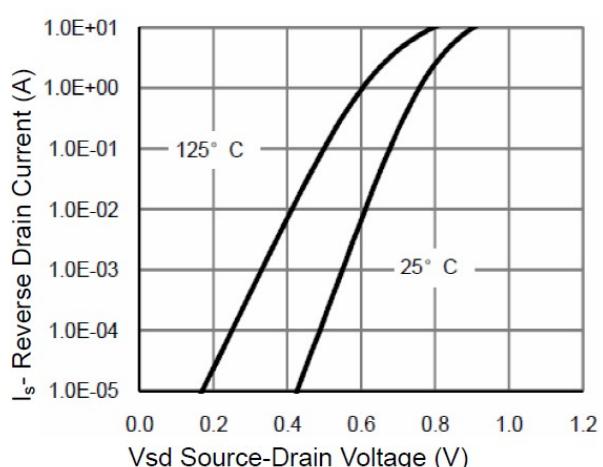
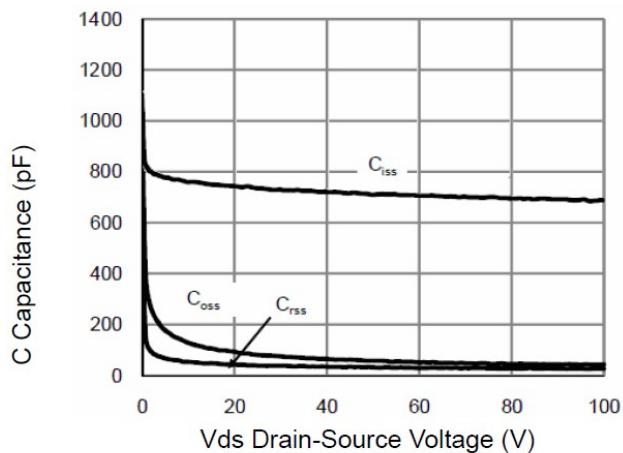
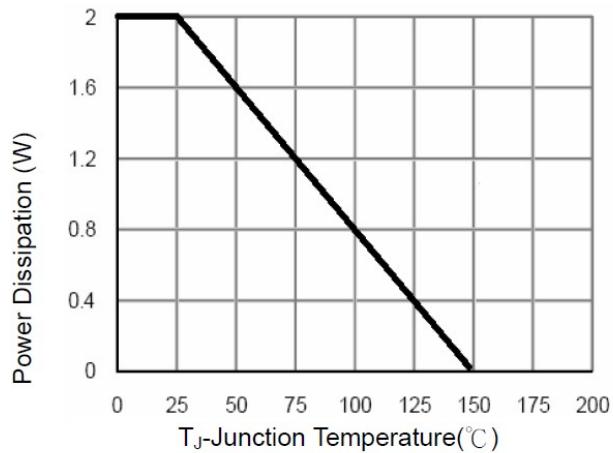
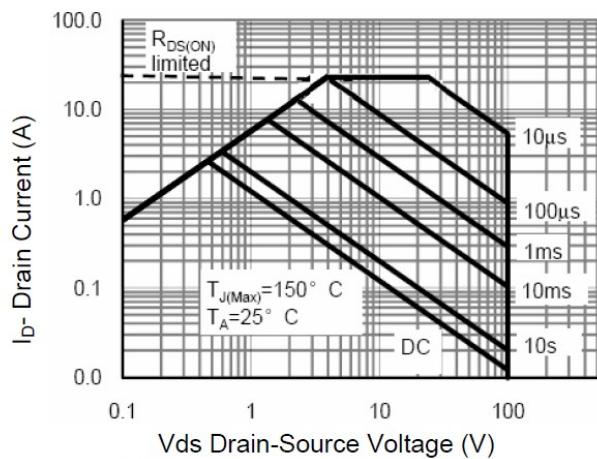
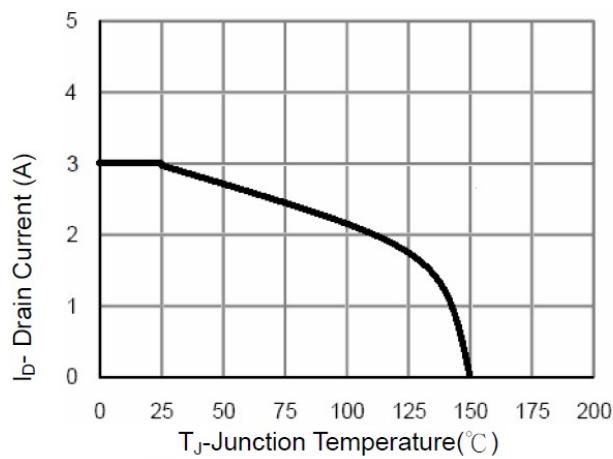
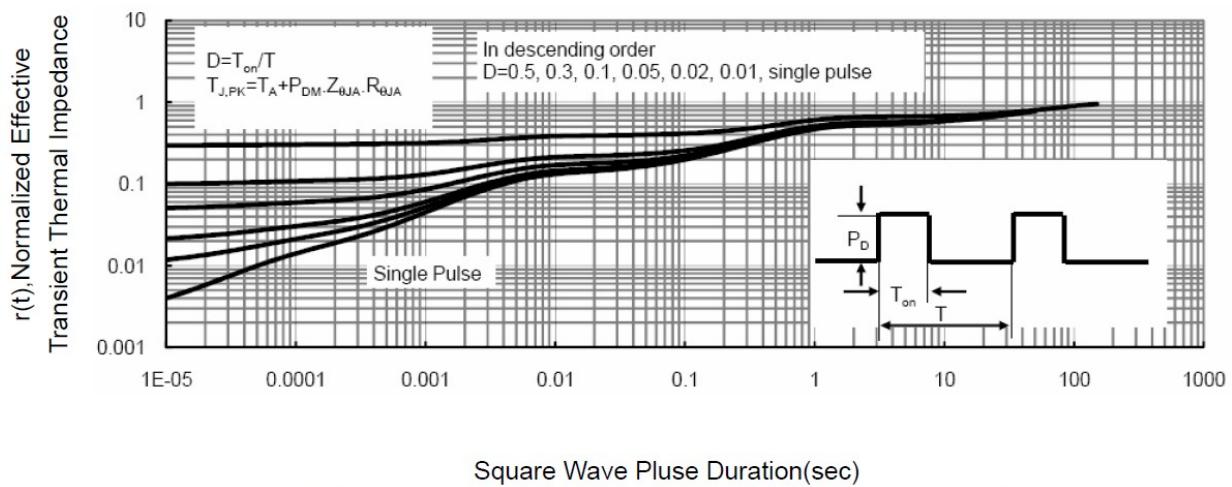
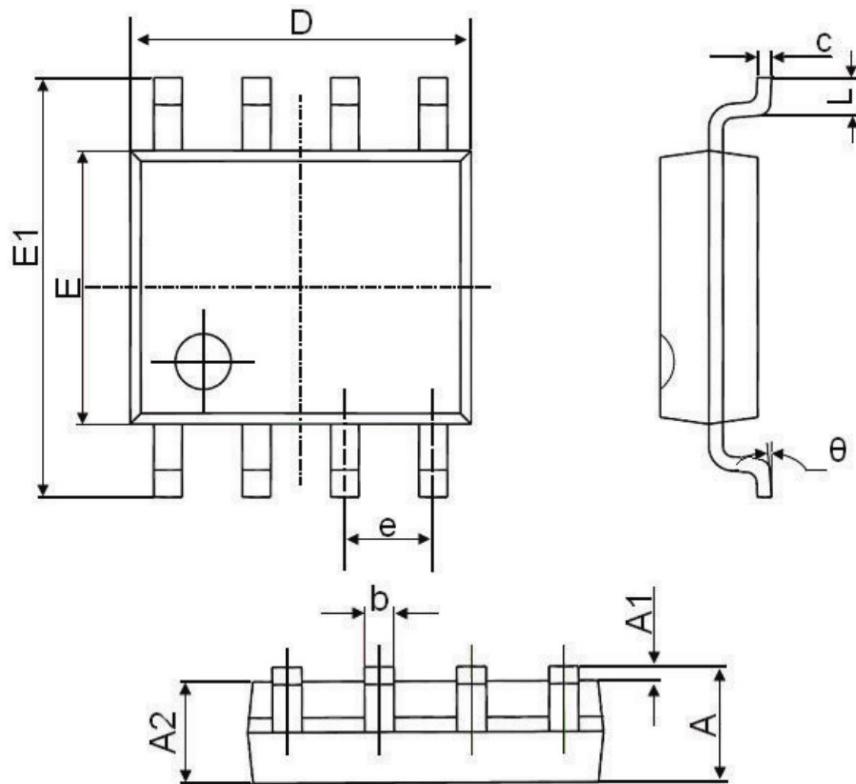


Figure 6 Source- Drain Diode Forward


Figure 7 Capacitance vs Vds

Figure 8 Power De-rating

Figure 9 Safe Operation Area

Figure 10 Current De-rating

Figure 11 Normalized Maximum Transient Thermal Impedance

SOP-8 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.250	1.650	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°